Lam Research Corporation To Present Innovative Productivity Solutions For Critical Applications At Semicon West

Lam Research Corporation To Present Innovative Productivity Solutions For Critical Applications At Semicon West FREMONT, Calif., July 11, 1998 - Lam Research Corporation (Nasdaq: LRCX), a leading supplier of wafer fabrication equipment to the worldwide semiconductor industry, today announced that it will present innovative productivity solutions for critical applications at SEMICON® West. The show focus will be enabling technologies for sub-0.25 micron lines and copper interconnect-such as etch and CMP for shallow trench isolation (STI), etch for dual damascene structures, and CMP for copper, oxide, and low k dielectrics. The show runs July 13-15, 1998 at the Moscone Center in San Francisco, California. Lam will exhibit in Booth 1632.

Lam will exhibit plasma etch process modules and show multimedia presentations, graphics, and videos of the equipment optimized for the targeted critical applications. Process equipment on display includes Lam's recently released TCP™ 9100PTX high-density dielectric etch module; the flexible, field-proven 4520XLE™ dielectric etch module; the TCP 9400PTX polysilicon/polycide and STI etch module; and the high-throughput TCP 9600PTX metal etch and microwave strip modules.

The integrated Teres™ multistation CMP system will be on display, demonstrating its STI and copper interconnect planarization and clean capability.

Lam's 4520XLE for dual damascene etch, and Lam's Teres for copper polish and post CMP clean will be featured in the Novellus "Best-of-Breed" copper interconnect display at Yerba Buena Gardens, located directly across from the Moscone Center South Hall. This site will exhibit an integrated copper interconnect process solution that combines dielectric etch and copper CMP processes from Lam with Novellus metal deposition processes.

Lam will also host a one-day technical symposium on July 14, where leading technologists from major semiconductor and equipment companies will be presenting work on low k dielectric etch, dual damascene patterning, nano-gate structure etch with ultrathin oxides, CMP and clean for STI applications, copper CMP and clean, and 300 mm development.

Lam Research Corporation is a leading supplier of wafer fabrication equipment and services to the world's semiconductor industry. The company provides processing solutions for dry etch, chemical mechanical planarization (CMP), and post CMP wafer clean, three essential steps in the fabrication of integrated circuits. Lam's headquarters are located in Fremont, California. The company's common stock trades on the Nasdaq National Market under the symbol LRCX. Lam's World Wide Web address is http://www.lamrc.com.

"Safe Harbor" Statement under the Private Securities Litigation Act of 1995: Except for historical information, this Press Release contains certain forward-looking statements and other prospective information relating to future events, including, but not limited to, statements relating to the release and significance of new products and technology. These statements and other information are subject to various risks, uncertainties and changes in condition, significance, value and effect that could cause results to differ materially and in ways not readily foreseeable, including, but not limited to, continued uncertainty surrounding the semiconductor industry generally, including the equipment industry specifically, and the development or acceptance of new products or product technologies, and other risks detailed from time to time in the company's SEC reports, including the report on Form 10-K for the year ended June 30, 1997, and the Form 10-Q for the quarter ended March 29, 1998. The company assumes no obligation to update the information in this Press Release.

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